

< High-power GaAs FET (small signal gain stage) >

MGF0915A

L & S BAND / 4.5W SMD non - matched

DESCRIPTION

The MGF0915A GaAs FET with an N-channel schottky Gate, is designed for use L & S band amplifiers.

FEATURES

- High output power
- Po=36.5dBm(TYP.) @f=1.9GHz,Pin=23dBm
- High power gain GLP=14.5dB(TYP.) @f=1.9GHz
- High power added efficiency nadd=50%(TYP.) @f=1.9GHz,Pin=23dBm
- Hermetic Package

APPLICATION

• For L & S Band power amplifiers

QUALITY

• GG

RECOMMENDED BIAS CONDITIONS

• Vds=10V • Ids=800mA • Rg=100Ω

Delivery -01:Tape & Reel(1K), -03:Trai(50pcs)

Absolute maximum ratings (Ta=25°C)

Symbol	Parameter	Ratings	Unit
VGDO	Gate to Drain Voltage	-15	V
VGSO	Gate to source voltage	-15	V
ID	Drain current	3000	mA
IGR	Reverse gate current	-10	mA
IGF	Forward gate current	21	mA
PT*1	Total power dissipation	18.7	W
Tch	Cannel temperature	175	°C
Tstg	Storage temperature	-65 to +175	°C

*1:Tc=25°C

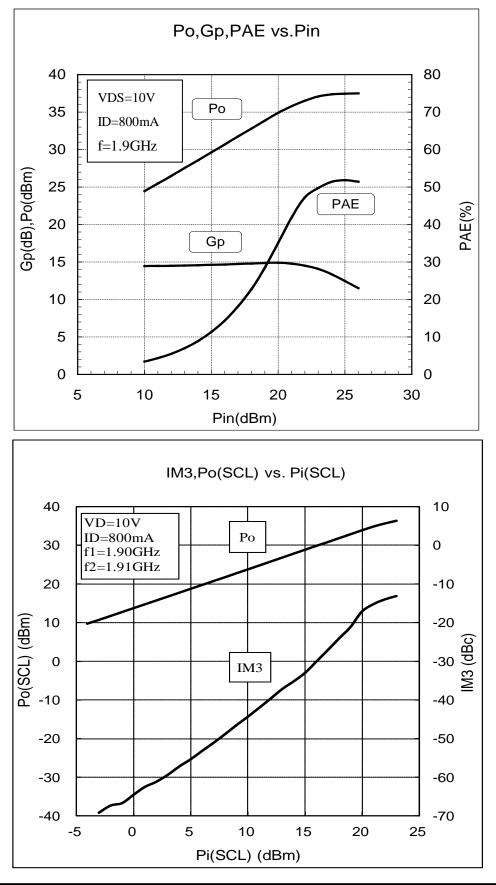
Electrical characteristics (Ta=25°C)

Symbol	Parameter	Test conditions	Limits		Unit	
			Min.	Тур.	Max.	
IDSS	Saturated drain current	nt VDS=3V,VGS=0V		2400	3000	mA
VGS(off)	Gate to source cut-off voltage	VDS=3V,ID=10mA	-1	-3	-5	V
gm	Transconductance	VDS=3V,ID=800mA	-	1000	-	mS
Po	Output power	VDS=10V,ID=800mA,f=1.9GHz	35	36.5	-	dBm
ηadd	Power added Efficiency	Pin=23dBm	-	50	-	%
GLP	Linear Power Gain	VDS=10V,ID=800mA,Pi=18dBm	13.0	14.5	-	dB
Rth(ch-c)	Thermal Resistance *1	ΔVf Method	-	5	8	°C/W

*1:Channel to case / Above parameters, ratings, limits are subject to change.

Fig.1

MGF0915A TYPICAL CHARACTERISTICS

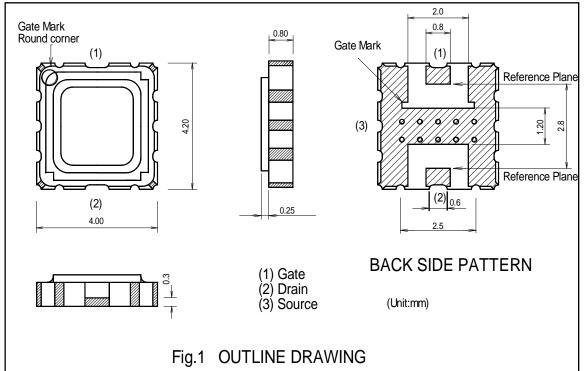


Publication Date : Dec., 2014 CSTG-16256

MITSUBISHI ELECTRIC CORPORATION

freq.	S	11	S	21	S	12	S	22	K	MAG/MSG
(MHz)	(mag)	(ang)	(mag)	(ang)	(mag)	(ang)	(mag)	(ang)		(dB)
600	0.948	-145.92	4.852	99.38	0.013	24.42	0.721	-177.51	0.38	25.72
1000	0.947	-161.85	2.941	86.78	0.015	26.56	0.717	-178.09	0.63	22.92
1400	0.946	-168.94	2.144	77.11	0.015	28.76	0.719	-178.44	0.84	21.55
1800	0.946	-173.55	1.746	69.39	0.016	30.92	0.725	-178.66	0.94	20.38
2200	0.945	-176.72	1.456	62.91	0.017	32.93	0.732	-178.82	1.03	18.23
2600	0.944	-178.89	1.211	57.13	0.018	34.72	0.739	-178.94	1.14	16.00
3000	0.942	178.80	1.032	51.69	0.019	36.22	0.745	-179.06	1.27	14.25
3400	0.939	177.37	0.934	46.34	0.020	37.37	0.749	-179.19	1.34	13.19
3800	0.935	174.73	0.888	40.95	0.022	38.13	0.751	-179.32	1.34	12.59
4200	0.930	171.44	0.836	35.45	0.024	38.46	0.751	-179.44	1.38	11.75
4600	0.925	167.90	0.759	29.81	0.027	38.33	0.749	-179.56	1.43	10.58
5000	0.918	164.36	0.798	24.04	0.031	37.72	0.745	-179.67	1.27	10.96
5400	0.911	160.93	0.730	18.15	0.035	36.59	0.740	-179.78	1.33	9.76
5800	0.903	157.60	0.715	12.14	0.039	34.92	0.732	179.67	1.32	9.23
6200	0.894	154.31	0.708	6.01	0.045	32.68	0.724	177.54	1.26	8.90
6600	0.884	150.88	0.707	-0.28	0.052	29.84	0.713	175.25	1.20	8.65
7000	0.871	147.10	0.711	-6.80	0.060	26.34	0.702	172.45	1.15	8.38
7400	0.855	142.73	0.721	-13.66	0.069	22.15	0.688	169.39	1.12	8.06
7800	0.833	137.52	0.739	-20.98	0.081	17.18	0.671	166.53	1.09	7.75
8200	0.807	131.21	0.765	-28.93	0.094	11.37	0.651	164.20	1.08	7.43
8600	0.778	123.58	0.802	-37.70	0.110	4.61	0.624	162.51	1.04	7.36
9000	0.748	114.45	0.849	-47.48	0.129	-3.21	0.590	161.19	1.00	8.18
9400	0.717	103.71	0.905	-58.48	0.152	-12.23	0.545	159.72	0.96	7.75
9800	0.688	91.34	0.964	-70.88	0.179	-22.60	0.487	157.44	0.93	7.31
10200	0.671	77.41	1.023	-84.83	0.211	-34.51	0.410	153.88	0.90	6.86
10600	0.672	62.12	1.072	-100.40	0.248	-48.17	0.311	149.13	0.86	6.36
11000	0.697	45.82	1.100	-117.62	0.293	-63.82	0.184	144.37	0.81	5.75
11400	0.746	29.03	1.095	-136.37	0.326	-81.74	0.021	-179.00	0.79	5.26
11800	0.812	12.43	1.038	-156.40	0.346	-102.24	0.194	-81.10	0.79	4.77
12200	0.877	-3.09	0.913	-177.29	0.346	-125.67	0.404	-95.22	0.79	4.21

MGF0915A S PARAMETERS (Ta=25°C,VD=10V,ID=800mA, Reference Plane see Fig.1)



Keep safety first in your circuit designs!

Mitsubishi Electric Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage. Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of non-flammable material or (iii) prevention against any malfunction or mishap.

Notes regarding these materials

- •These materials are intended as a reference to assist our customers in the selection of the Mitsubishi semiconductor product best suited to the customer's application; they do not convey any license under any intellectual property rights, or any other rights, belonging to Mitsubishi Electric Corporation or a third party.
- •Mitsubishi Electric Corporation assumes no responsibility for any damage, or infringement of any third-party's rights, originating in the use of any product data, diagrams, charts, programs, algorithms, or circuit application examples contained in these materials.
- •All information contained in these materials, including product data, diagrams, charts, programs and algorithms represents information on products at the time of publication of these materials, and are subject to change by Mitsubishi Electric Corporation without notice due to product improvements or other reasons. It is therefore recommended that customers contact Mitsubishi Electric Corporation or an authorized Mitsubishi Semiconductor product distributor for the latest product information before purchasing a product listed herein.

The information described here may contain technical inaccuracies or typographical errors. Mitsubishi Electric Corporation assumes no responsibility for any damage, liability, or other loss rising from these inaccuracies or errors.

Please also pay attention to information published by Mitsubishi Electric Corporation by various means, including the Mitsubishi Semiconductor home page (http://www.MitsubishiElectric.com/).

- •When using any or all of the information contained in these materials, including product data, diagrams, charts, programs, and algorithms, please be sure to evaluate all information as a total system before making a final decision on the applicability of the information and products. Mitsubishi Electric Corporation assumes no responsibility for any damage, liability or other loss resulting from the information contained herein.
- •Mitsubishi Electric Corporation semiconductors are not designed or manufactured for use in a device or system that is used under circumstances in which human life is potentially at stake. Please contact Mitsubishi Electric Corporation or an authorized Mitsubishi Semiconductor product distributor when considering the use of a product contained herein for any specific purposes, such as apparatus or systems for transportation, vehicular, medical, aerospace, nuclear, or undersea repeater use.
- •The prior written approval of Mitsubishi Electric Corporation is necessary to reprint or reproduce in whole or in part these materials.
- •If these products or technologies are subject to the Japanese export control restrictions, they must be exported under a license from the Japanese government and cannot be imported into a country other than the approved destination.

Any diversion or re-export contrary to the export control laws and regulations of Japan and/or the country of destination is prohibited.

•Please contact Mitsubishi Electric Corporation or an authorized Mitsubishi Semiconductor product distributor for further details on these materials or the products contained therein.